

NC275LR NO CLEAN LIQUID FLUX

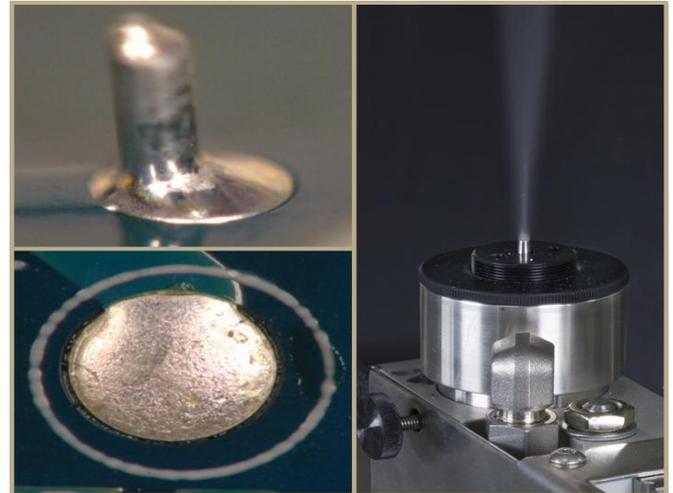
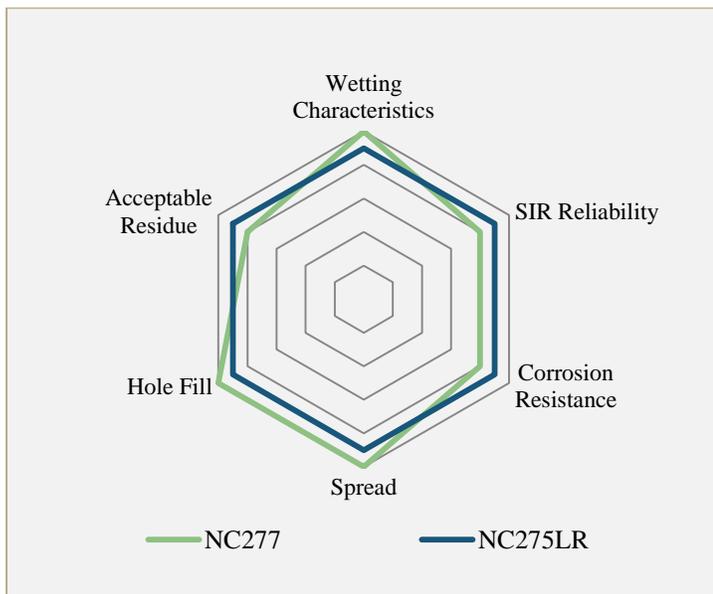
FEATURES

- VOC-Free per ASTM D3960-98
- Passes IPC J-STD-004B
- Broad Process Window
- Withstands Extended Dwell Time
- Fast Wetting
- REACH/RoHS Compliant
- Low Post-Soldering Residue

DESCRIPTION

NC275LR is a water-based, halide-free, no-clean liquid flux formulated to offer a wide process window with excellent wetting even on hard-to-wet and OSP surfaces. NC275LR offers a durable activator system accommodating a variety of process parameters and applications, including soldering with tin-silver-copper, tin-silver, tin-copper, and other lead free alloys. In addition, NC275LR is a low-odor, low-fume flux and provides rapid solvent evaporation. NC275LR is safe for palletized selective wave soldering and point-to-point selective soldering. NC275LR residues may be left on the circuit board after processing; residue removal is not required.

CHARACTERISTICS



HANDLING & STORAGE

Parameter	Time	Temperature
Sealed Shelf Life	9 months	Room Temperature

NC275LR has a sealed shelf life of 9 months when stored at room temperature. Keep away from sunlight as it may degrade product. NC275LR is shipped ready-to-use, no mixing necessary. Do not mix used and unused chemicals in the same container. Reseal any opened containers. Storage conditions range from 4-40°C (40-100°F).

APPLICATION

NC275LR is formulated for application via spray or mist. Foaming is not recommended. NC275LR is ready to use directly from its container. When spray fluxing, proper flux coverage and uniformity are imperative. A dry flux coating of 500-1500 micrograms per square inch is recommended as a starting point. The use of nitrogen is not required but acceptable.

PROCESS GUIDELINES

Using thermocouples attached to the top of the PCB, the topside assembly temperature should be between 100-135°C (212-275°F). It is important that the flux be dry prior to entering the wave regardless of temperature or spattering will occur. Smoking may occur and is considered normal if it is not excessive. Recommended contact time with the wave is dependent on wave configuration, pot temperature, alloy type and thermal mass of the assembly with 4-7 seconds being typical. For processing assistance, please contact AIM Technical Support by visiting <http://www.aimsolder.com/technical-support-contacts>.

CLEANING

NC275LR can be cleaned using a saponifier or chemical cleaners. Contact AIM for additional information. Deionized water is recommended for the final rinse.

SAFETY

Use with adequate ventilation and proper personal protective equipment. Refer to the accompanying Safety Data Sheet for any specific emergency information. Do not dispose of any hazardous materials in non-approved containers.

TEST DATA SUMMARY

Name	Test Method	Results	
IPC Flux Classification	J-STD-004	ORL0	
IPC Flux Classification	J-STD-004B 3.3.1	ORL0	
Name	Test Method	Results	Image
Copper Mirror	J-STD-004B 3.4.1.1 IPC-TM-650 2.3.32	LOW	
Corrosion	J-STD-004B 3.4.1.2 IPC-TM-650 2.6.15	PASS	
Quantitative Halides	J-STD-004B 3.4.1.3 IPC-TM-650 2.3.28.1	Br 0.00% Cl: 0.00%	
Qualitative Halides, Silver Chromate	J-STD-004B 3.5.1.1 IPC-TM-650 2.3.33	PASS	

Name	Test Method	Results	Image
Qualitative Halides, Fluoride Spot	J-STD-004B 3.5.1.2 IPC-TM-650 2.3.35.1	No fluoride	
Surface Insulation Resistance	J-STD-004B 3.4.1.4 IPC-TM-650 2.6.3.7	PASS	
Flux Solids, Nonvolatile Determination	J-STD-004B 3.4.2.1 IPC-TM-650 2.3.34	3.16% Typical	
Acid Value Determination	J-STD-004B 3.4.2.2 IPC-TM-650 2.3.13	25.5 mg KOH per gram flux Typical	
Flux Specific Gravity Determination	J-STD-004B 3.4.2.3 ASTM D-1298	1.00 Typical	
pH (1% solution /water)	ASTM D5464 ASTM G51	2.71 Typical	
Visual	J-STD-004B 3.4.2.5	PASS	